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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
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3848

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7590

09/26/2008

EXAMINER

CEHIC, KENAN

ART UNIT

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2616

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PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No. 10/791,914	Applicant(s) CHEE ET AL.	
	Examiner KENAN CEHIC	Art Unit 2616	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 09 June 2008.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 2-6 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 2-6 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413) |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____ |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08) | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Response to Arguments

1. Applicant's arguments with respect to claim 2-6 have been considered but are moot in view of the new ground(s) of rejection.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

The factual inquiries set forth in *Graham v. John Deere Co.*, 383 U.S. 1, 148 USPQ 459 (1966), that are applied for establishing a background for determining obviousness under 35 U.S.C. 103(a) are summarized as follows:

1. Determining the scope and contents of the prior art.
 2. Ascertaining the differences between the prior art and the claims at issue.
 3. Resolving the level of ordinary skill in the pertinent art.
 4. Considering objective evidence present in the application indicating obviousness or nonobviousness.
2. Claim 2-6 are rejected under 35 U.S.C. 103(a) as being unpatentable over Freeman (US 4,862,399) and English, ADA 95: The Craft of Object-Oriented Programming, "Glossary".

For claim 2, Freeman discloses a method for use in verification of a device (and col 12 lines 57 through col 13 line 43 "method of determining...output test pattern is reliably reproduced from a set of test input pattern....digital circuit...screening said simulated...input patterns to one another and retaining only those...pattern which applies...discarding those digital circuit input patterns...applying said compared

...patterns to an actual manufactured digital circuit") comprising:
providing a plurality of packet classes (see fig 2; Large, Redundant Chip-level Testset;
col 9 lines 40 through col 10 line 40 " test patterns...produces the necessary test patterns
to be applied...to block under test...test patterns applied ...all of the test patterns...
..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk...Pk represents a
fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test
patterns....all block level tests");
providing indications (see fig 4; Already detected, detected inclusive and fig 2; List of
Test...already found" and Retain Chip-Level Test...update...List...already found")
which may be of a first or second state (see fig 4; Already detected, detected inclusive
and fig 2; List of Test...already found" and Retain Chip-Level
Test...update...List...already found"; checkmarks for each pattern; see col 9 lines 35
through col 10 line 40 "pattern is not needed...only those patter) , for each of the
plurality of packet classes (see fig 2; Large, Redundant Chip-level Testset; see fig 4;
Testset, Fault; col 9 lines 40 through col 10 line 40 " test patterns...produces the
necessary test patterns to be applied...to block under test...test patterns applied ...all of
the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-
Pk..faults column lists all the patterns Pk to be selected...Pk represents a fault test
pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test
patterns....all block level tests");
generating a packet (see fig 2; Large, Redundant Chip-level Testset; see fig 4; Testset,
Fault; col 9 lines 40 through col 10 line 40 " test patterns...produces the necessary test

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patterns to be applied...to block under test...test patterns applied ...all of the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk..faults column lists all the patterns Pk to be selected...Pk represents a fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests"); if the indication of the packet class of the generated packet is in the first state (see fig. 4, "Already detected"; "This pattern", "Detected Inclusive", checkmarks for the patterns; see col 9 lines 35 through col 10 line 40 "two sets of chip level test vectors yield the same test at the block-level...tests is discarded....only one...is retained...Pattern Pc is then compared to all other chip level test pattern...") testing the device (see fig 2; Small, Nonredundant Chip-level testset and col 9 line 35 through col 10 line 40 "pattern is noted...those patterns...are kept...until the test pattern Pc contain...results in a efficient testset which exhaustively test the chip in a practical way" And col 11 lines 1-50 " and col 12 lines 57 through col 13 line 43 "method of determining...output test pattern is reliably reproduced from a set of test input pattern....digital circuit...screening said simulated...input patterns to one antoher and retaining only those...pattern which applies...discarding those digital circuit input patterns...applying said comparedpatterns to an actual manufactured digital circuit") if the indication of the packet class of the generated packet is in the first state (see fig. 4; "Already detected"; "This pattern", "Detected Inclusive", checkmarks for the patterns; see col 9 lines 35 through col 10 line 40 "two sets of chip level test vectors yield the same test at the block-level...tests is discarded....only one...is retained...Pattern Pc is then compared to all other chip level test pattern..."), noting/making/changing an indication

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for the packet class (see fig 4; "This pattern", "Detected Inclusive" and fig 2; List of Test...already found" and Retain Chip-Level Test...update...List...already found"; col 9 line 35 through col 10 line 40 "pattern is noted if it detects a new fault...those patterns that may be useful in detecting a fault are kept...test is added to the list")

For claim 3, A method for use in verification of a device (and col 12 lines 57 through col 13 line 43 "method of determining...output test pattern is reliably reproduced from a set of test input pattern....digital circuit...screening said simulated...input patterns to one another and retaining only those...pattern which applies...discarding those digital circuit input patterns...applying said comparedpatterns to an actual manufactured digital circuit") comprising:

providing a plurality of packet classes (see fig 2; Large, Redundant Chip-level Testset; col 9 lines 40 through col 10 line 40 " test patterns...produces the necessary test patterns to be applied...to block under test...test patterns applied ...all of the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk...Pk represents a fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests");

providing a indications (see fig 4; Already detected, detected inclusive and fig 2; List of Test...already found" and Retain Chip-Level Test...update...List...already found"), which may be of a first or a second state (see fig 4; Already detected, detected inclusive and fig 2; List of Test...already found" and Retain Chip-Level

Test...update...List...already found"; checkmarks for each pattern; see col 9 lines 35 through col 10 line 40 "pattern is not needed...only those patter), for each of the plurality

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of packet classes (see fig 2; Large, Redundant Chip-level Testset; see fig 4; Testset, Fault; col 9 lines 40 through col 10 line 40 “ test patterns...produces the necessary test patterns to be applied...to block under test...test patterns applied ...all of the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk..faults column lists all the patterns Pk to be selected...Pk represents a fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests”);

generating a packet (see fig 2; Large, Redundant Chip-level Testset; see fig 4; Testset, Fault; col 9 lines 40 through col 10 line 40 “ test patterns...produces the necessary test patterns to be applied...to block under test...test patterns applied ...all of the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk..faults column lists all the patterns Pk to be selected...Pk represents a fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests”); if the indication of the packet class of the generated

packet is in the first state (see fig. 4, “Already detected”; “This pattern”, "Detected Inclusive", checkmarks for the patterns; see col 9 lines 35 through col 10 line 40 “two sets of chip level test vectors yield the same test at the block-level...tests is

discarded....only one...is retained...Pattern Pc is then compared to all other chip level test pattern...” testing the device (see fig 2; Small, Nonredundant Chip-level testset and col 9 line 35 through col 10 line 40 "pattern is noted...those patterns...are kept...until the test pattern Pc contain...results in a efficient testset which exhaustively test the chip in a practical way” And col 11 lines 1-50 " and col 12 lines 57 through col 13 line 43 "method

of determining...output test pattern is reliably reproduced from a set of test input pattern....digital circuit...screening said simulated...input patterns to one another and retaining only those...pattern which applies...discarding those digital circuit input patterns...applying said comparedpatterns to an actual manufactured digital circuit");if the indication of the packet class of the generated packet is in the second state (see fig. 4, "Already detected"; "This pattern", "Detected Inclusive", checkmarks for the patterns; see col 9 lines 35 through col 10 line 40 "two sets of chip level test vectors yield the same test at the block-level...tests is discarded...only one...is retained...Pattern Pc is then compared to all other chip level test pattern..."), not testing the device (see fig 2; retain chip-level test, "small, nonredundant chip-level testset"; col 9 lines 40 through col 10 line 40 "remaining patterns of no interest are discarded...tests is discarded...additional pattern PC" is redundant and can be discarded..." col 12 lines 57 through col 13 line 43 " discarding those digital circuit input patterns...applying said comparedpatterns to an actual manufactured digital circuit")

For claim 4, Freeman discloses A method for use in verification of a device (and col 12 lines 57 through col 13 line 43 "method of determining...output test pattern is reliably reproduced from a set of test input pattern....digital circuit...screening said simulated...input patterns to one another and retaining only those...pattern which applies...discarding those digital circuit input patterns...applying said comparedpatterns to an actual manufactured digital circuit") comprising: providing a plurality of packet classes (see fig 2; Large, Redundant Chip-level Testset; col 9 lines 40 through col 10 line 40 " test patterns...produces the necessary test patterns to be applied...to block

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under test...test patterns applied ...all of the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk...Pk represents a fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests”);

providing an indication (see fig 4; Already detected, detected inclusive and fig 2; List of Test...already found” and Retain Chip-Level Test...update...List...already found”), which may be of a first or a second state (see fig 4; Already detected, detected inclusive and fig 2; List of Test...already found” and Retain Chip-Level Test...update...List...already found”; checkmarks for each pattern; see col 9 lines 35 through col 10 line 40 “pattern is not needed...only those patter), for each of the plurality of packet classes (see fig 2; Large, Redundant Chip-level Testset; see fig 4; Testset, Fault; col 9 lines 40 through col 10 line 40 “ test patterns...produces the necessary test patterns to be applied...to block under test...test patterns applied ...all of the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk..faults column lists all the patterns Pk to be selected...Pk represents a fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests”);

generating a packet (see fig 2; Large, Redundant Chip-level Testset; see fig 4; Testset, Fault; col 9 lines 40 through col 10 line 40 “ test patterns...produces the necessary test patterns to be applied...to block under test...test patterns applied ...all of the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk..faults column lists all the patterns Pk to be selected...Pk represents a fault test

pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests”);

if the indication of the packet class of the generated packet is in the second state (see fig. 4, “Already detected”; “This pattern”, “Detected Inclusive”, checkmarks for the patterns; see col 9 lines 35 through col 10 line 40 “two sets of chip level test vectors yield the same test at the block-level...tests is discarded....only one...is retained...Pattern Pc is then compared to all other chip level test pattern...”), not testing the device (see fig 2; retain chip-level test, “small, nonredundant chip-level testset”; col 9 lines 40 through col 10 line 40 “remaining patterns of no interest are discarded...tests is discarded...additional pattern PC” is redundant and can be discarded...” col 12 lines 57 through col 13 line 43 “discarding those digital circuit input patterns...applying said comparedpatterns to an actual manufactured digital circuit”)

For claim 5, Freeman discloses A method for use in verification of a device (and col 12 lines 57 through col 13 line 43 “method of determining...output test pattern is reliably reproduced from a set of test input pattern....digital circuit...screening said simulated...input patterns to one another and retaining only those...pattern which applies...discarding those digital circuit input patterns...applying said comparedpatterns to an actual manufactured digital circuit”) comprising:

(a) providing a plurality of packet classes (see fig 2; Large, Redundant Chip-level Testset; col 9 lines 40 through col 10 line 40 “ test patterns...produces the necessary test patterns to be applied...to block under test...test patterns applied ...all of the test patterns... ..obtain a test pattern....TESTSET represents a list of all patterns P1-Pk...Pk

represents a fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests”);

(b) providing an indication (see fig 4; Already detected, detected inclusive and fig 2; List of Test...already found” and Retain Chip-Level Test...update...List...already found”), which may be of a first or a second state (see fig 4; Already detected, detected inclusive and fig 2; List of Test...already found” and Retain Chip-Level

Test...update...List...already found”; checkmarks for each pattern; see col 9 lines 35 through col 10 line 40 “pattern is not needed...only those patter), for each of the plurality of packet classes (see fig 2; Large, Redundant Chip-level Testset; see fig 4; Testset, Fault; col 9 lines 40 through col 10 line 40 “ test patterns...produces the necessary test patterns to be applied...to block under test...test patterns applied ...all of the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk..faults column lists all the patterns Pk to be selected...Pk represents a fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests”);

(c) generating a packet (see fig 2; Large, Redundant Chip-level Testset; see fig 4; Testset, Fault; col 9 lines 40 through col 10 line 40 “ test patterns...produces the necessary test patterns to be applied...to block under test...test patterns applied ...all of the test patterns... ..obtain a test pattern.....TESTSET represents a list of all patterns P1-Pk..faults column lists all the patterns Pk to be selected...Pk represents a fault test pattern...tests are determined....sets of chip-level test vectors...Pattern PC...test patterns....all block level tests”);

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(d) if the indication of the packet class of the generated packet is in the second state (see fig. 4, "Already detected"; "This pattern", "Detected Inclusive", checkmarks for the patterns; see col 9 lines 35 through col 10 line 40 "two sets of chip level test vectors yield the same test at the block-level...tests is discarded....only one...is retained...Pattern Pc is then compared to all other chip level test pattern..."), not testing the device (see fig 2; retain chip-level test, "small, nonredundant chip-level testset"; col 9 lines 40 through col 10 line 40 "remaining patterns of no interest are discarded...tests is discarded...additional pattern PC" is redundant and can be discarded..." col 12 lines 57 through col 13 line 43 " discarding those digital circuit input patterns...applying said comparedpatterns to an actual manufactured digital circuit")

;(e) if the indication of the packet class of the generated packet is in the first state (see fig. 4; "Already detected"; "This pattern", "Detected Inclusive", checkmarks for the patterns; see col 9 lines 35 through col 10 line 40 "two sets of chip level test vectors yield the same test at the block-level...tests is discarded....only one...is retained...Pattern Pc is then compared to all other chip level test pattern..."), testing the device (see fig 2; Small, Nonredundant Chip-level testset and col 9 line 35 through col 10 line 40 "pattern is noted...those patterns...are kept...until the test pattern Pc contain...results in a efficient testset which exhaustively test the chip in a practical way" And col 11 lines 1-50 " and col 12 lines 57 through col 13 line 43 "method of determining...output test pattern is reliably reproduced from a set of test input pattern....digital circuit...screening said simulated...input patterns to one another and retaining only those...pattern which applies...discarding those digital circuit input patterns...applying said compared

...patterns to an actual manufactured digital circuit")

noting/making/changing an indication for the packet class of the generated packet (see fig 4; "This pattern", "Detected Inclusive" and fig 2; List of Test...already found" and Retain Chip-Level Test...update...List...already found"; col 9 line 35 through col 10 line 40 "pattern is noted if it detects a new fault...those patterns that may be useful in detecting a fault are kept...test is added to the list")

For claim 6, Freeman discloses further comprising repeating steps (c) through (e) thereof (see col 9 line 25 through col 10 line 40 "all block level test are determined....test is added to the list ...screened...procedure is repeated").

While Freeman discloses indicators for a packet class (see fig 4), Freeman fails to explicitly disclose:

For claim 2 and 3, flag, having two states, as indicators, and changing the state of a flag.

For claim 5, injection flag, having two states, as indicators, and changing the state of a injection flag.

English from the same or similar field of endeavor discloses:

For claim 2 and 3, flag, having two states, as indicators, and changing the state of a flag (see page 5; "Flag": A Boolean value which can be "set" to True or 'reset' to False").

For claim 5, injection flag, having two states, as indicators, and changing the state of a injection flag (see page 5; "Flag": A Boolean value which can be "set" to True or 'reset' to False").

It would have been obvious to one of the ordinary skill in the art at the time of the invention to modify the system of Freeman by using the features, as taught by English, in

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order to provide an means / programming technique (using flags) which indicates a certain state of a program/variables with minimal storage (memory) use. Through the use of flags a system/program (like the one of Freeman) can use known flags to indicate a certain property/state of either the program/ variable with minimal memory and processing resources.

Furthermore, each of the claimed elements was known in the art, and a person of ordinary skill in the art could have combined the use of flags into the program/method of Freeman each element would have preformed the same function as it did separately. The use of flags in the Freeman system would not change the operation of the Freeman system, as the use of flags is merely using variables in a program that indicate a certain state and one of ordinary skill would have recognized that the results of the combination would have been predictable.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to KENAN CEHIC whose telephone number is (571)270-3120. The examiner can normally be reached on Monday through Friday 8:00-5:30.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, KWANG BIN YAO can be reached on (571) 272-3182. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

/Kenan Cehic/
Examiner, Art Unit 2616

/Kwang B. Yao/
Supervisory Patent Examiner, Art Unit 2616